

STL70N4LLF5

Automotive-grade N-channel 40 V, 6.1 mΩ typ., 18 A STripFET™ F5 Power MOSFET in a PowerFLAT™ 5x6 package

Datasheet - production data

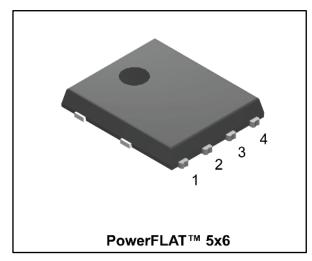
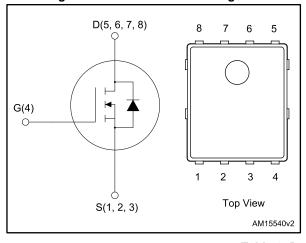


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	ID
STL70N4LLF5	40 V	6.7 mΩ	18 A



- AEC-Q101 qualified
- Low on-resistance R_{DS(on)}
- High avalanche ruggedness
- Low gate drive power loss
- Wettable flank package

Applications

• Switching applications

Description

This N-channel Power MOSFET is developed using the STripFET™ F5 technology and has been optimized to achieve very low on-state resistance, contributing to a FoM that is among the best in its class.

Table 1: Device summary

Order code	Marking	Package	Packing
STL70N4LLF5	70N4LLF5	PowerFLAT™ 5x6	Tape and reel

Contents STL70N4LLF5

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STL70N4LLF5 Electrical ratings

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source voltage	40	V
V_{GS}	Gate-source voltage	± 22	V
I _D ⁽¹⁾	Drain current (continuous) at T _C = 25 °C	70	
I _D ⁽¹⁾	Drain current (continuous) at T _c = 100 °C	44	
I _D ⁽²⁾	Drain current (continuous) at T _{pcb} = 25 °C	18	Α
I _D ⁽²⁾	Drain current (continuous) at T _{pcb} = 100 °C	11.5	
I _{DM} ⁽¹⁾⁽³⁾	Drain current (pulsed)	72	
P _{TOT} ⁽¹⁾	Total dissipation at T _C = 25 °C	72	W
P _{TOT} ⁽²⁾	Total dissipation at T _{pcb} = 25 °C	4.8	VV
T _{stg}	Storage temperature range	FF to 17F	°C
TJ	Operation junction temperature range	-55 to 175	

Notes:

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case	2.08	°C/W
R _{thj-pcb} ⁽¹⁾	Thermal resistance junction-pcb 31.3		C/VV

Notes:

Table 4: Avalanche data

Symbol	Parameter	Value	Unit
l _{AV}	Not-repetitive avalanche current (pulse width limited by T _{jmax.})	9	Α
Eas	Single pulse avalanche energy (starting $T_J = 25$ °C, $I_D = I_{AV}$, $V_{DD} = 24$ V)	470	mJ

 $^{^{(1)} \}mbox{The value}$ is rated according to $R_{\mbox{\scriptsize thj-c}}.$

 $[\]ensuremath{^{(2)}} The value is rated according to <math display="inline">R_{thj\text{-pcb.}}$

⁽³⁾Pulse width limited by safe operating area

 $^{^{(1)}}$ When mounted on FR-4 board of 1 inch², 2oz Cu, t < 10 s

Electrical characteristics STL70N4LLF5

2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Table 5: On/off-states

Symbol	Parameter Test conditions		Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	I _D = 250 μA, V _{GS} = 0 V	40			V
IDSS	Zero gate voltage drain current	$V_{GS} = 0 V$ $V_{DS} = 40 V$			1	
IDSS	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}$ $V_{DS} = 40 \text{ V}, T_J = 125 \text{ °C }^{(1)}$			10	μА
Igss	Gate-body leakage current	V _{GS} = ± 22 V, V _{DS} = 0 V			±100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1		2.5	V
D	Static drain-source	V _G S = 10 V, I _D = 9 A		6.1	6.7	m0
R _{DS(on)}	on-resistance	V _{GS} = 4.5 V, I _D = 9 A		7.6	9.0	mΩ

Notes:

Table 6: Dynamic

Symbol	Parameter Test conditions		Min.	Тур.	Max.	Unit
C _{iss}	Input capacitance		ı	1570	ı	pF
Coss	Output capacitance	V _{DS} = 25 V, f = 1 MHz,	-	257	-	pF
Crss	Reverse transfer capacitance	$V_{GS} = 0 V$	-	32	-	pF
Qg	Total gate charge	V _{DD} = 15 V, I _D = 18 A,	ı	12.9	1	nC
Qgs	Gate-source charge	V _G S = 4.5 V	ı	3.9	ı	nC
Q _{gd}	Gate-drain charge	(see Figure 14: "Test circuit for gate charge behavior")	1	5.3	ı	nC
Rg	Gate input resistance	f = 1 MHz, gate DC bias = 0 V, test signal level = 20 mV, I _D = 0 A	ı	1.5	-	Ω

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time	V _{DD} = 15 V, I _D = 9 A,	1	14	ı	ns
tr	Rise time	$R_G = 4.7 \Omega$, $V_{GS} = 10 V$	-	42	-	ns
t _{d(off)}	Turn-off delay time	(see Figure 13: "Test circuit for	-	37	-	ns
t _f	Fall time	resistive load switching times"	-	5.2	-	ns

 $^{^{(1)}}$ Defined by design, not subject to production test

Table 8: Source-drain diode

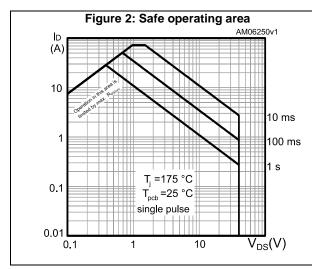
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current		-		18	Α
I _{SDM} ⁽¹⁾	Source-drain current pulsed		-		72	Α
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} = 18 A, V _{GS} = 0 V			1.1	V
t _{rr}	Reverse recovery time		-	27.2		ns
Qrr	Reverse recovery charge	$I_{SD} = 18 \text{ A, di/dt} = 100 \text{ A/µs,}$ $V_{DD} = 25 \text{ V, T}_{J} = 150 \text{ °C}$	-	24.5		nC
I _{RRM}	Reverse recovery current	VDD = 20 V, 13 = 100 O	-	1.8		Α

Notes:

 $[\]ensuremath{^{(1)}}\mbox{Pulse}$ width limited by safe operating area.

 $^{^{(2)}\}text{Pulsed:}$ pulse duration = 300 $\mu\text{s},$ duty cycle 1.5%

2.2 Electrical characteristics (curves)



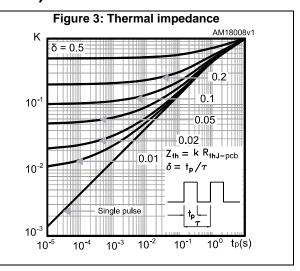


Figure 4: Output characteristics

ID

AM06251v1

160

120

4 V

80

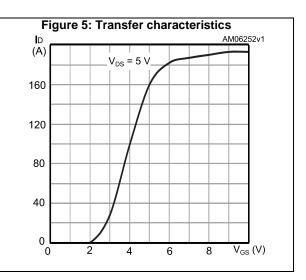
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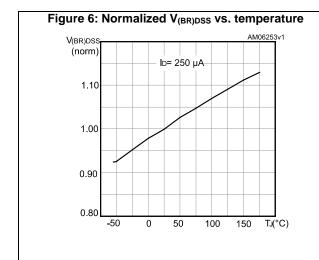
0

2

4 6

8 V_{DS}(V)





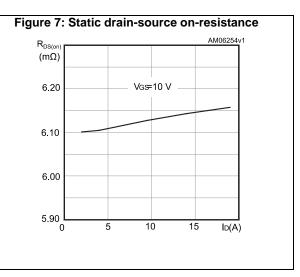


Figure 8: Gate charge vs. gate-source voltage

VGS
(V)
12
| VDD=15 V |
|D=18 A |
10
8
6
4
2
0
0 5 10 15 20 25 Qg(nC)

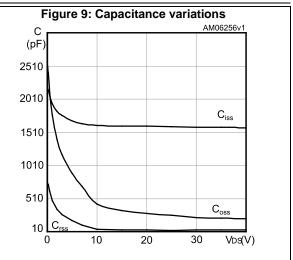
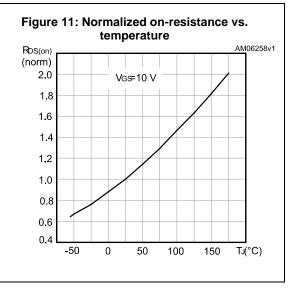
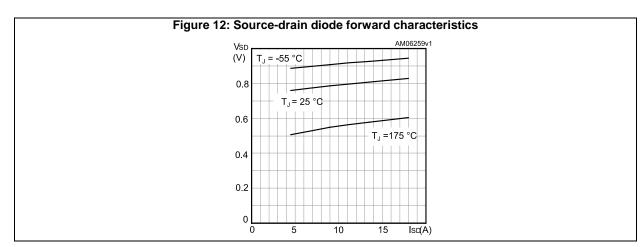


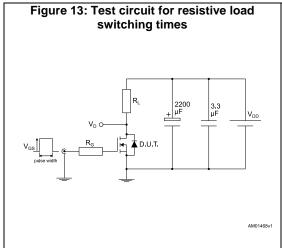
Figure 10: Normalized gate threshold voltage vs. temperature $V_{GS(th)}$ (norm) Vos=Vgs 1.2 lo= 250 μA 1.0 0.8 0.6 0.4 -50 0 50 100 150 TJ(°C)





Test circuits STL70N4LLF5

3 Test circuits



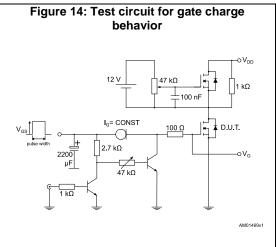
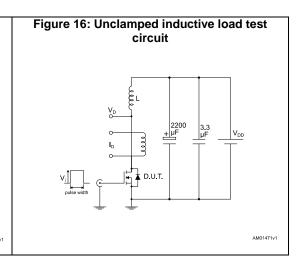
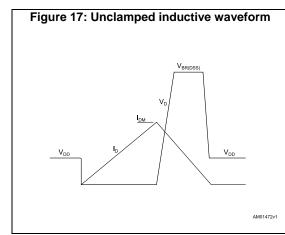
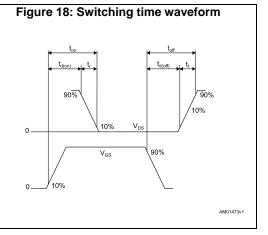


Figure 15: Test circuit for inductive load switching and diode recovery times







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4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

4.1 PowerFLAT™ 5x6 single island WF type C package information

Figure 19: PowerFLAT™ 5x6 WF type C package outline

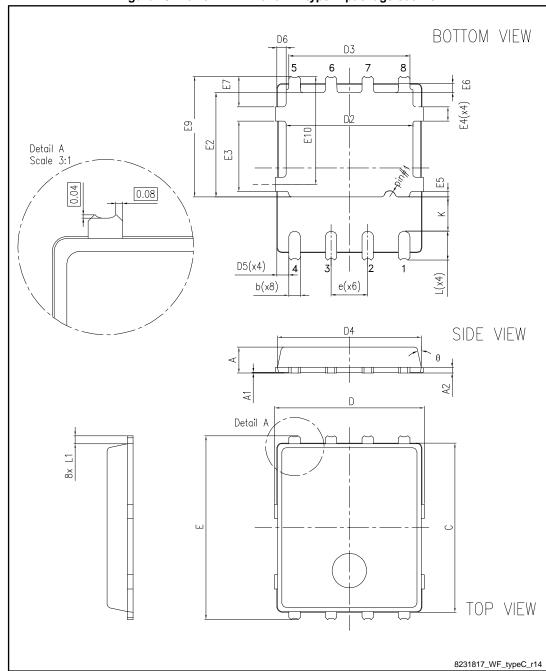
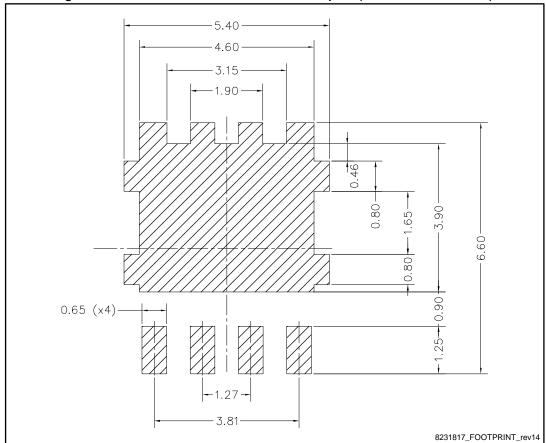


Table 9: PowerFLAT™ 5x6 WF type C mechanical data

Di		mm	
Dim.	Min.	Тур.	Max.
А	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
С	5.80	6.00	6.10
D	5.00	5.20	5.40
D2	4.15		4.45
D3	4.05	4.20	4.35
D4	4.80	5.00	5.10
D5	0.25	0.40	0.55
D6	0.15	0.30	0.45
е		1.27	
Е	6.20	6.40	6.60
E2	3.50		3.70
E3	2.35		2.55
E4	0.40		0.60
E5	0.08		0.28
E6	0.20	0.325	0.45
E7	0.85	1.00	1.15
E9	4.00	4.20	4.40
E10	3.55	3.70	3.85
K	1.05		1.35
L	0.90	1.00	1.10
L1	0.175	0.275	0.375
θ	0°		12°





STL70N4LLF5 Package information

4.2 Packing information

Figure 21: PowerFLAT™ 5x6 WF tape (dimensions are in mm)

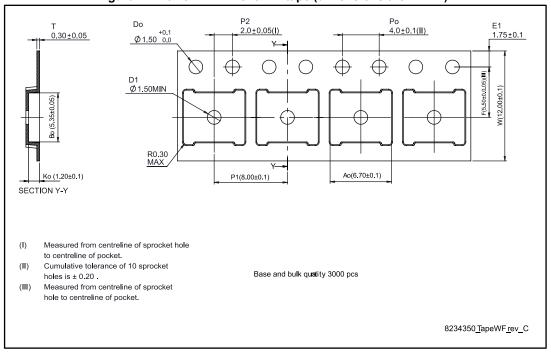
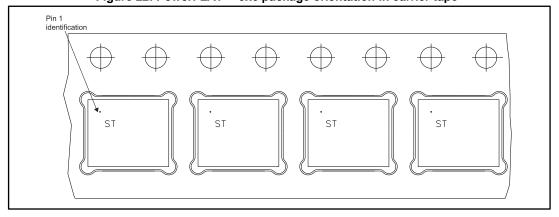


Figure 22: PowerFLAT™ 5x6 package orientation in carrier tape



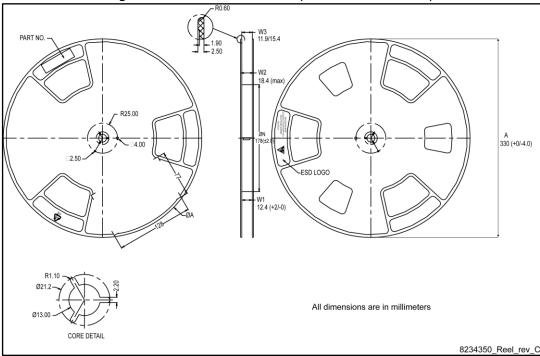


Figure 23: PowerFLAT™ 5x6 reel (dimensions are in mm)

STL70N4LLF5 Revision history

5 Revision history

Table 10: Document revision history

Date	Revision	Changes
01-Dec-2008	1	First release.
18-Jul-2011	2	Section 4: Package mechanical data has been modified: - Added Table 9: PowerFLAT™ 5x6 type S-C mechanical data - Added Figure 19: PowerFLAT™ 5x6 type S-C mechanical data - Added PowerFLAT™ 5x6 type C-B mechanical data - Added PowerFLAT™ 5x6 type C-B drawing Minor text changes.
21-Dec-2011	3	Section 4: Package mechanical data has been modified.
25-Jan-2013	4	 Table 1: Device summary has been updated. -Minor text changes. -Changed: Figure 1 -Added Section 5: Packaging mechanical data.
12-Feb-2013	5	-Updated T _J and T _{stg} in Table 2: Absolute maximum ratings. — Updated Section 4: Package mechanical data and Figure 22: PowerFLAT™ 5x6 package orientation in carrier tape.
24-May-2013	6	- Modified: title and Section 4: Package mechanical data - Minor text changes.
17-Dec-2014	7	 Modified: Figure 2 and 3 Updated: Figure 13, 14, 15 and 16 Updated: Section 4: Package mechanical data and Section 5: Packaging mechanical data Minor text changes.
08-Apr-2016	8	 Updated Section 4: Package information and Section 4.1: Packing information Minor text changes.
22-Sep-2016	9	Updated V _{GS(th)} in <i>Table 5: "On/off-states"</i> .

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